

COMPLETE LISTING OF THE CLAIMS

The following lists all of the claims that are or were in the above-identified patent application. The status identifiers respectively provided in parentheses following the claim numbers indicate the current statuses of the claims.

1-6. (Canceled)

7. (Currently Amended) A method for fabricating a light source comprising:

mounting a chip having a primary light source on a substrate, said primary light source emitting light of a first wavelength;

connecting power terminals on said chip to corresponding power terminals on said substrate for powering said primary light source; and

mounting a performed transparent cap over said chip, said cap comprising a wavelength-converting material for converting a portion of said light of said first wavelength to a second wavelength, wherein said transparent cap comprises a spherical surface ~~of constant~~ and has a constant thickness.

8-16. (Canceled)

17. (Previously Presented) The method of Claim 7 wherein said transparent cap comprises a material in which said wavelength-converting material is soluble.

18. (Previously Presented) The method of Claim 7 wherein said transparent cap comprises glass.

19. (New) The method of Claim 7 wherein said primary light source comprises an LED.

20. (New) The method of Claim 7, wherein said primary light source comprises a laser diode.

21. (New) The method of Claim 7, wherein said transparent cap comprises a phosphor material suspended in a clear compound.

22. (New) The method of Claim 7, wherein said transparent cap comprises a planar sheet of a single crystal phosphor.
23. (New) The method of Claim 7, wherein said transparent cap comprises a inverted cavity, said chip being on a concave side of said cavity.
24. (New) The method of Claim 7, wherein said transparent cap comprises a planar sheet having a constant thickness.